

N-Channel Enhancement Mode Power MOSFET

Description

The MSF6N40 is a N-channel enhancement-mode MOSFET, providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness. The TO-220F package is universally preferred for all commercial-industrial applications

Features

- · Low On Resistance
- · Simple Drive Requirement
- · Low Gate Charge
- · Fast Switching Characteristic
- RoHS compliant package

Application

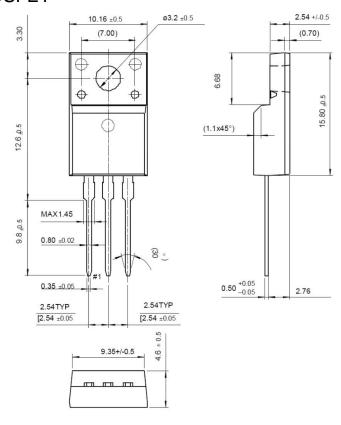
- Adapter
- · Switching Mode Power Supply

Packing & Order Information

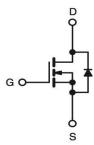
50/Tube; 1,000/Box







Graphic symbol



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings						
Symbol	Parameter	Value	Unit			
V_{DSS}	Drain-Source Voltage	400	V			
V _{GS}	Gate-Source Voltage	±30	V			
I _D	Drain Current -Continuous (TC=25°C)	5.5	Α			
	Drain Current -Continuous (TC=100°C)	3.5	A			
I_{DM}	Drain Current Pulsed	16.4	A			
E _{AS}	Single Pulsed Avalanche Energy	240	mJ			
E _{AR}	Repetitive Avalanche Energy	10	mJ			
dv/dt	Peak Diode Recovery dv/dt	5.5	V/ns			



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Absolute Maximum Ratings					
Symbol	Parameter	Value	Unit		
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C		
TPKG	Maximum Temperature for Soldering @ Package Body for 10 seconds	260	°C		
P _D	Total Power Dissipation (TC=25°C)	38	W		
	Derating Factor above 25 °C	0.3	W/°C		
T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C		
T _J	Storage Temperature	150	°C		

Notes;

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} =5.5A, V_{DD} =50V, L=8mH, V_{G} =10V, starting TJ=+25°C.
- 3. $I_{SD} \le 5.5A$, $dI/dt \le 100A/\mu s$, $V_{DD} \le BVDSS$, starting TJ=+25°C.

Thermal Characteristics					
Symbol	Parameter	Max.	Units		
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	3.3	°C/W		
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	C/VV		

Static Characteristics					
Symbol	Test Conditions	Min	Тур.	Max.	Units
V_{GS}	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0		4.0	V
*R _{DS(ON)}	$V_{GS} = 10 \text{ V}$, $I_D = 2.75 \text{ A}$		0.8	1.0	Ω
BV _{DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu A$	400			V
$\Delta BV_{DSS}/\Delta T_{J}$	$I_D = 250\mu A$, Referenced to 25°C		0.4		
I _{DSS}	$V_{DS} = 400 \text{ V}$, $V_{GS} = 0 \text{ V}$ $V_{DS} = 320 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_j = 125 ^{\circ}\text{C}$			1 10	uA
I _{GSSF}	$V_{DS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
I _{GSSR}	V _{DS} = -30 V, V _{DS} = 0 V			-100	nA

Dynamic Characteristics						
Symbol	Test Conditions	Min	Тур.	Max.	Units	
$t_{d(on)}$			20	50	ns	
t _r	$V_{DS} = 200 \text{ V}, I_{D} = 5.5 \text{ A},$		50	110	ns	
t _{d(off)}	$R_G = 25 \Omega$		90	190	ns	
tf			55	120	ns	



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Dynamic Characteristics					
Symbol	Test Conditions	Min	Тур.	Max.	Units
C_{ISS}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{MHz}$		670	870	pF
C _{OSS}			95	125	pF
C _{RSS}			16	21	pF
Q_g	V _{DS} = 320 V,I _D = 5.5 A, V _{GS} = 10 V		25	33	nC
Q_{gs}			5.0		
Q_{gd}			10.0		

Source-Drain Diode Characteristics					
Symbol	Test Conditions	Min	Тур.	Max.	Units
I _S				5.5	
I _{SM}				22	A
V _{SD}	IF = 5.5 A , V _{GS} = 0			1.5	V
t _{rr}	JE 5 5 A V 0 4 JE 44 400 A / -		220		ns
Q _{rr}	$IF = 5.5 \text{ A}$, $V_{GS} = 0$, $dIF/dt=100A/μs$		2		uC

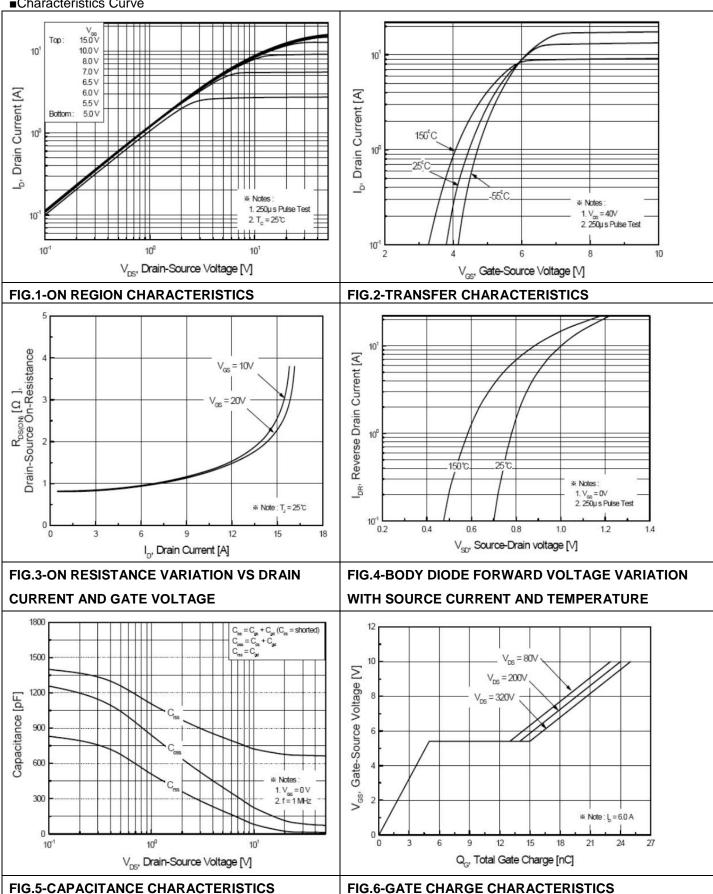
Notes;

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} =5.5 A, V_{DD} =50V, R_{G} =25W, Starting TJ =25°C
- 3. I_{SD} \leq 5.5 A, di/dt \leq 300A/ μ s, V_{DD} \leq BVDSS , Starting TJ =25 °C
- 4. Pulse Test : Pulse Width ≤ 300µs, Duty Cycle ≤ 2%
- 5. Essentially Independent of Operating Temperature



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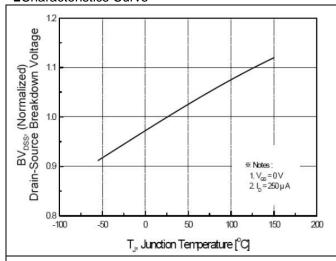
■Characteristics Curve





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■Characteristics Curve



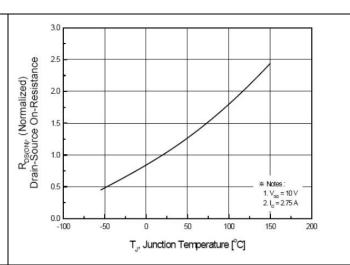


FIG.7-BREAKDOWN VOLTAGE VARIATION VS TEMPERATURE

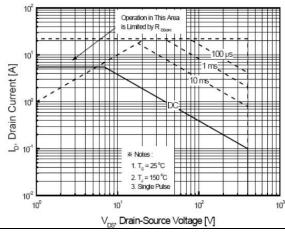


FIG.8-ON-RESISTANCE VARIATION VS TEMPERATURE

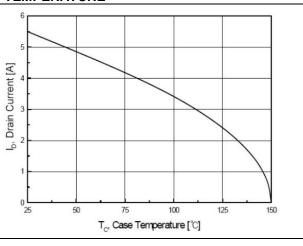


FIG.9-MAXIMUM SAFE OPERATING AREA

FIG.10-MAXIMUM DRAIN CURRENT VS CASE TEMPERATURE

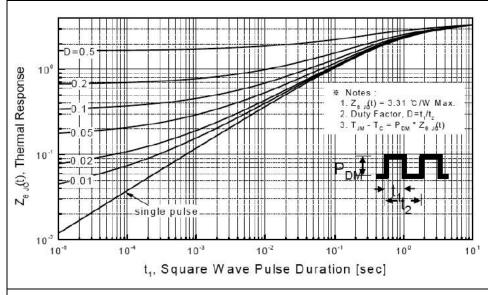


FIG.11-TRANSIENT THERMAL RESPONSE CURVE



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